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Diode

Silicon Carbide Schottky Diode

IDH16G120C5

5th Generation thinQ!™ 1200 V SiC Schottky Diode

Final Datasheet

Rev. 2.0 2015-09-03

Industrial Power Control



5th Generation thinQ!™ 1200 V SiC Schottky Diode

thinQ![™] SiC Schottky Diode

Features:

- Revolutionary semiconductor material Silicon Carbide
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant

Benefits

- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size / cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- RelatedLinks: <u>www.infineon.com/sic</u>

Applications

- Solar inverters
- Uninterruptable power supplies
- Motor drives
- Power Factor Correction

Package pin definitions

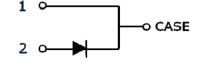
- Pin 1 and backside cathode
- Pin 2 anode



Key Performance and Package Parameters

Туре	V _{DC}	I _F	Q _c	T _{j,max}	Marking	Package
IDH16G120C5	1200V	16A	57nC	175°C	D1612C5	PG-TO220-2-1

1) J-STD20 and JESD22







5th Generation thinQ!™ 1200 V SiC Schottky Diode

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5th Generation thinQ!™ 1200 V SiC Schottky Diode

Maximum ratings

Parameter	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM}	1200	V	
Continues forward current for $R_{th(j-c,max)}$ $T_c = 145^{\circ}C, D=1$ $T_c = 135^{\circ}C, D=1$ $T_c = 25^{\circ}C, D=1$	I _F	16 19 40	A	
Surge non-repetitive forward current, sine halfwave $T_{\rm C}$ =25°C, t _p =10ms $T_{\rm C}$ =150°C, t _p =10ms	I _{F,SM}	140 120	A	
Non-repetitive peak forward current $T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 10 \ \mu{\rm s}$	I _{F,max}	850	А	
i ² t value $T_{\rm C} = 25^{\circ}$ C, $t_{\rm p}$ =10 ms $T_{\rm C} = 150^{\circ}$ C, $t_{\rm p}$ =10 ms	∫ i²dt	99 71	A²s	
Diode d <i>v</i> /d <i>t</i> ruggedness <i>V</i> _B =0960V	dv/dt	80	V/ns	
Power dissipation $T_{\rm C} = 25^{\circ}{\rm C}$	P _{tot}	250	W	
Operating and storage temperature	$T_{\rm j}$; $T_{\rm stg}$	-55175	٥°	
Soldering temperature, wavesoldering only allowed at leads, 1.6mm (0.063 in.) from case for 10 s	T _{sold}	260	°C	
Mounting torque M3 and M4 screws	М	0.7	Nm	

Thermal Resistances

Parameter	Symbol	Conditions		Value		Unit
Falamelei	Symbol	Conditions	min.	typ.	max.	onit
Characteristic						
Diode thermal resistance, junction – case	R _{th(j-c)}		-	0.46	0.60	K/W
Thermal resistance, junction – ambient	R _{th(j-a)}	leaded	-	-	62	K/W



Electrical Characteristics

Static Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions min.		Value	Unit	
Farameter			min.	typ.	max.	Onit
Static Characteristic						
DC blocking voltage	V _{DC}	$T_{\rm j} = 25^{\circ}{\rm C}$	1200	-	-	V
Diode forward voltage	V _F	<i>I</i> _F = 16A, <i>T</i> _j =25°C	-	1.65	1.95	V
Didde forward voltage		<i>I</i> _F = 16A, <i>T</i> _j =150°C	-	2.25	2.85	
Reverse current	I _R	<i>V</i> _R =1200V, <i>T</i> _j =25°C		5.5	80	μΑ
		V _R =1200V, <i>T</i> _j =150°C		28	410	

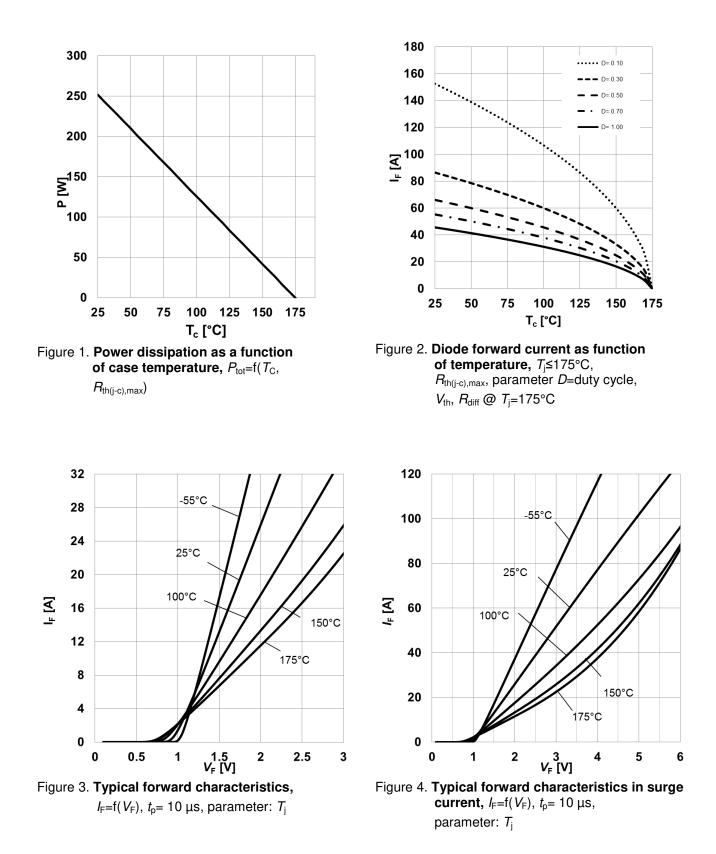
Dynamic Characteristics, at $T_j=25^{\circ}C$, unless otherwise specified

Parameter	Symbol	Conditions		Value		
Falameter	Symbol		min.	typ.	max.	Unit
Dynamic Characteristics						
Total capacitive charge	Q _C	$V_{\rm R}=800 \text{V}, \ T_{\rm j}=150^{\circ}\text{C}$ $Q_{\rm C} = \int_{V_{\rm R}}^{V_{\rm R}} C(V) dV$	-	57	-	nC
		0		700		
Total Capacitance	С	V _R =1 V, <i>f</i> =1 MHz V _R =400 V, <i>f</i> =1 MHz	-	730 52	-	pF
		<i>V</i> _R =800 V, <i>f</i> =1 MHz	-	40	-	



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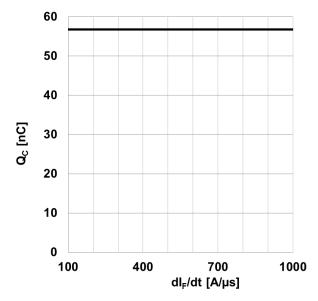
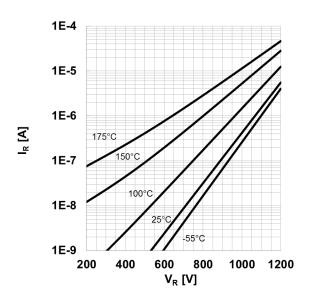
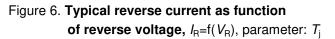
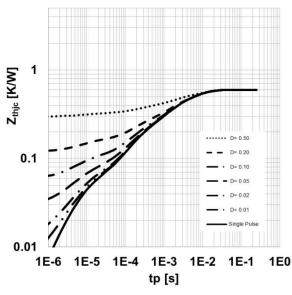
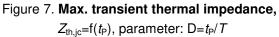


Figure 5. Typical capacitive charge as function of current slope¹, $Q_{C}=f(dI_{F}/dt)$, $T_{j}=150$ °C 1) Only capacitive charge, guaranteed by design.









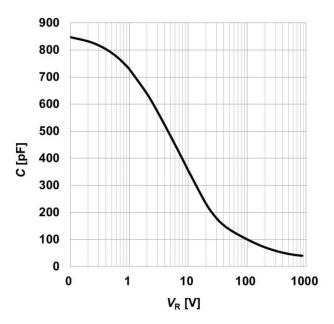
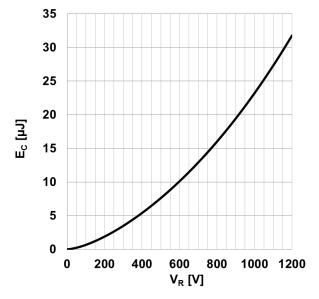
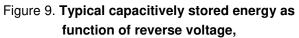


Figure 8. **Typical capacitance as function of** reverse voltage, *C*=f(*V*_R); *T*_j=25°C; *f*=1 MHz





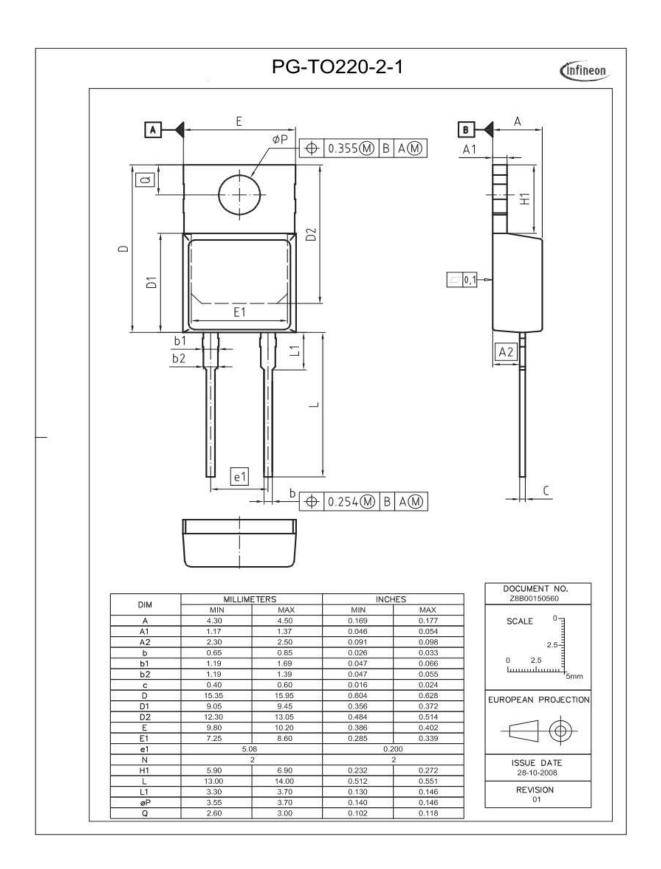


$$E_C = \int_0^{V_R} C(V) V dV$$



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Revision History

IDH16G120C5

Revision: 2015-09-03, Rev. 2.0

Previous Revision:					
Revision	Date	Subjects (major changes since last version)			
2.0	-	Final data sheet			

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